DATA SHEET

74ABT16245B
74ABTH16245B
16-bit bus transceiver (3-State)

Product data
Supersedes data of 1998 Feb 25

2002 Dec 13

Philips
Semiconductors

PHILIPS

16-bit bus transceiver (3-State)

74ABT16245B
74ABTH16245B

FEATURES

- 16-bit bidirectional bus interface
- Power-up 3-State
- Multiple V_{CC} and GND pins minimize switching noise
- 3-State buffers
- Output capability: +64 mA / –32 mA
- Latch-up protection exceeds 500 mA per JEDEC Std 17
- Live insertion/extraction permitted
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- 74ABTH16245B incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs

DESCRIPTION

The 74ABT16245B high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT16245B device is a dual octal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. The control function implementation minimizes external timing requirements. The device features two Output Enable ($1\overline{OE}$, $2\overline{OE}$) inputs for easy cascading and two Direction (1DIR, 2DIR) inputs for direction control.

Two options are available, 74ABT16245B which does not have the bus hold feature and the 74ABTH16245B which incorporates the bus hold feature.

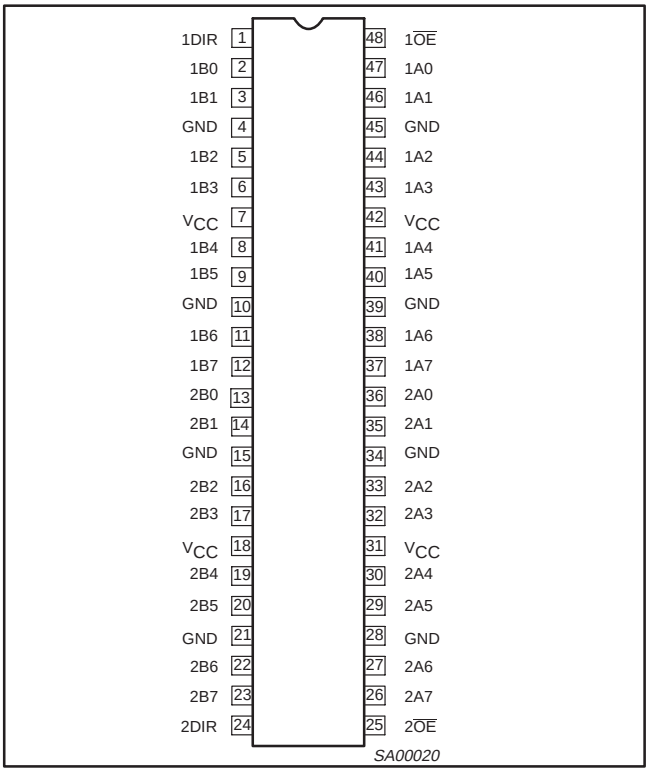
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25 °C; GND = 0 V	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay nAx to nBx or nBx to nAx	C_L = 50 pF; V_{CC} = 5 V	2.0 2.3	ns
C_{IN}	Input capacitance	V_I = 0 V or V_{CC}	4	pF
$C_{I/O}$	I/O pin capacitance	V_O = 0 V or V_{CC}; 3-State	7	pF
I_{CCZ}	Quiescent supply current	Outputs disabled; V_{CC} = 5.5 V	500	µA
I_{CCL}		Output Low; V_{CC} = 5.5 V	10	mA

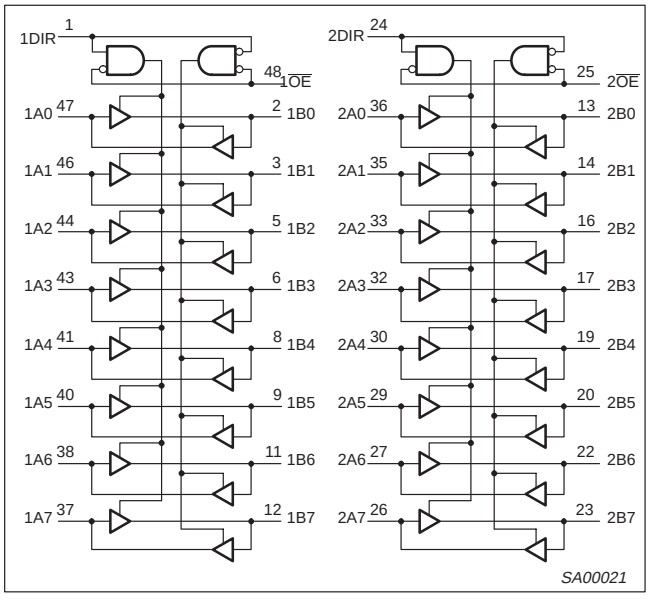
ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	PART NUMBER	DWG NUMBER
48-Pin Plastic SSOP Type III	–40 °C to +85 °C	74ABT16245BDL	SOT370-1
48-Pin Plastic TSSOP Type II	–40 °C to +85 °C	74ABT16245BDGG	SOT362-1
48-Pin Plastic SSOP Type III	–40 °C to +85 °C	74ABTH16245BDL	SOT370-1

PIN CONFIGURATION



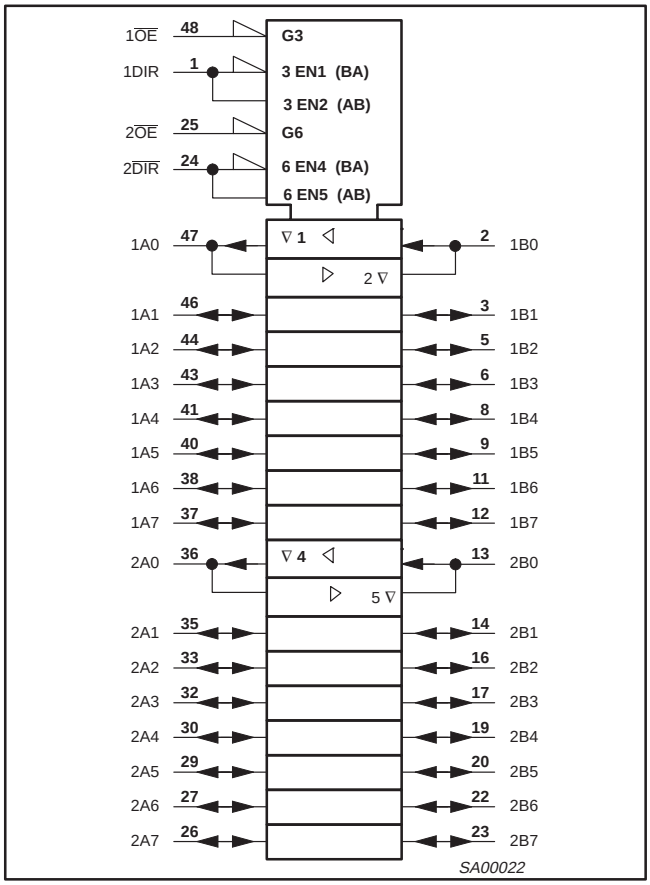
LOGIC SYMBOL



PIN DESCRIPTION

SYMBOL	PIN NUMBER	NAME AND FUNCTION
1DIR, 2DIR	1, 24	Direction control inputs (Active-HIGH)
1A0 – 1A7, 2A0 – 2A7	47, 46, 44, 43 41, 40, 38, 37 36, 35, 33, 32 30, 29, 27, 26	Data inputs/outputs (A side)
1B0 – 1B7 2B0 – 2B7	2, 3, 5, 6 8, 9, 11, 12 13, 14, 16, 17 19, 20, 22, 23	Data inputs/outputs (B side)
$1\overline{OE}$, $2\overline{OE}$	48, 25	Output enables
GND	4, 10, 15, 21 28, 34, 39, 45	Ground (0 V)
V_{CC}	7, 18, 31, 42	Positive supply voltage

LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS	
$n\overline{OE}$	nDIR	nAx	nBx
L	L	A = B	Inputs
L	H	Inputs	B = A
H	X	Z	Z

H = HIGH voltage level
L = LOW voltage level
X = Don't care
Z = High impedance "off" scale

ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$ V	–18	mA
V_I	DC input voltage[3]		–1.2 to +7.0	V
I_{OK}	DC output diode current	$V_O < 0$ V	–50	mA
V_{OUT}	DC output voltage[3]	output in Off or HIGH state	–0.5 to +5.5	V
I_{OUT}	DC output current	output in LOW state	128	mA
		output in HIGH state	–64	
T_{stg}	Storage temperature range		–65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V_{CC}	DC supply voltage	4.5	5.5	V
V_I	Input voltage	0	V_{CC}	V
V_{IH}	HIGH-level input voltage	2.0		V
V_{IL}	LOW-level Input voltage		0.8	V
I_{OH}	HIGH-level output current		–32	mA
I_{OL}	LOW-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T_{amb}	Operating free-air temperature range	–40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T_{amb} = +25 °C			T_{amb} = –40 °C to +85 °C		
			Min	Typ	Max	Min	Max	
V_{IK}	Input clamp voltage	V_{CC} = 4.5 V; I_{IK} = –18 mA		–0.9	–1.2		–1.2	V
V_{OH}	High-level output voltage	V_{CC} = 4.5 V; I_{OH} = –3 mA; V_I = V_{IL} or V_{IH}	2.5	2.9		2.5		V
		V_{CC} = 5.0 V; I_{OH} = –3 mA; V_I = V_{IL} or V_{IH}	3.0	3.4		3.0		V
		V_{CC} = 4.5 V; I_{OH} = –32 mA; V_I = V_{IL} or V_{IH}	2.0	2.4		2.0		V
V_{OL}	Low-level output voltage	V_{CC} = 4.5 V; I_{OL} = 64 mA; V_I = V_{IL} or V_{IH}		0.42	0.55		0.55	V
I_I	Input leakage current	V_{CC} = 5.5 V; V_I = GND or 5.5 V Control pins		±0.01	±1.0		±1.0	µA
I_{HOLD}	Bus hold current A and B inputs 74ABTH16245B	V_{CC} = 4.5 V; V_I = 0.8 V	50			50		µA
		V_{CC} = 5.5 V; V_I = 2.0 V	–75			–75		
		V_{CC} = 5.5 V; V_I = 0 to 5.5 V	±500					
I_{OFF}	Power-off leakage current	V_{CC} = 0.0 V; V_O or $V_I \leq$ 4.5 V		±5.0	±100		±100	µA
I_{PU}/I_{PD}	Power-up/down 3-State output current	V_{CC} = 2.0 V; V_O = 0.5 V; V_I = GND or V_{CC}; V_{OE} = Don't care		±5.0	±50		±50	µA
$I_{IH}+I_{OZH}$	3-State output HIGH current	V_{CC} = 5.5 V; V_O = 5.5 V; V_I = V_{IL} or V_{IH}		0.1	10		10	µA
$I_{IL}+I_{OZL}$	3-State output LOW current	V_{CC} = 5.5 V; V_O = 0.0 V; V_I = V_{IL} or V_{IH}		0.1	10		10	µA
I_{CEX}	Output high leakage current	V_{CC} = 5.5 V; V_O = 5.5 V; V_I = GND or V_{CC}		5.0	50		50	µA
I_O	Output current[1]	V_{CC} = 5.5 V; V_O = 2.5 V	–50	–92	–180	–50	–180	mA
I_{CCH}	Quiescent supply current	V_{CC} = 5.5 V; Outputs High, V_I = GND or V_{CC}		0.30	0.70		0.70	mA
I_{CCL}		V_{CC} = 5.5 V; Outputs Low, V_I = GND or V_{CC}		10	19		19	mA
I_{CCZ}		V_{CC} = 5.5 V; Outputs 3-State; V_I = GND or V_{CC}		0.30	0.70		0.70	mA
ΔI_{CC}	Additional supply current per input pin[2]	Outputs enabled, one data input at 3.4 V, other inputs at V_{CC} or GND; V_{CC} = 5.5 V		400	700		700	µA
		Outputs disabled, one data input at 3.4 V, other inputs at V_{CC} or GND; V_{CC} = 5.5 V		100	250		250	µA
		Control pins, outputs disabled, one enable input at 3.4 V, other inputs at V_{CC} or GND; V_{CC} = 5.5 V		400	700		700	µA

NOTES:
1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
2. This is the increase in supply current for each input at 3.4 V.
3. This is the bus hold overdrive current required to force the input to the opposite logic state.

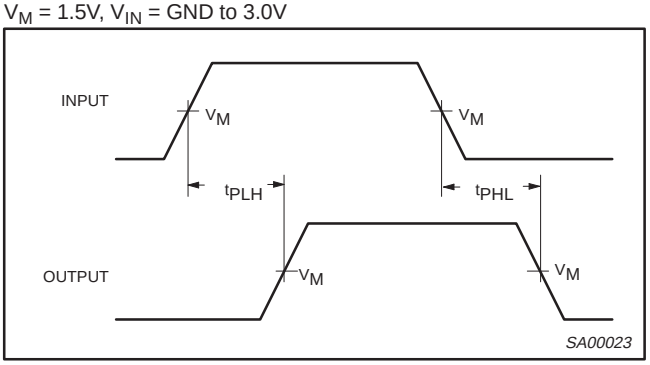
AC CHARACTERISTICS

GND = 0V; $t_R = t_F$ = 2.5ns; C_L = 50pF, R_L = 500Ω

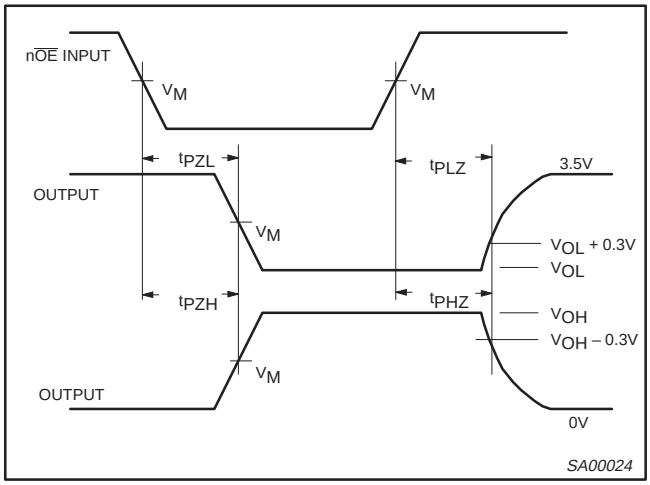
SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			T_{amb} = +25 °C, V_{CC} = +5.0 V			T_{amb} = –40 °C to +85 °C, V_{CC} = +5.0 V ±0.5 V		
			Min	Typ	Max	Min	Max	
t_{PLH} t_{PHL}	Propagation delay nAx to nBx or nBx to nAx	1	1.0 1.0	2.0 2.3	3.2 3.5	1.0 1.0	3.5 4.0	ns
t_{PZH} t_{PZL}	Output enable time to High and Low level	2	1.0 1.7	3.1 4.0	4.4 5.2	1.0 1.7	5.1 6.1	ns
t_{PHZ} t_{PLZ}	Output disable time from High and Low level	2	1.7 1.5	3.5 3.2	4.9 4.4	1.7 1.5	5.4 5.0	ns

AC WAVEFORMS

V_M = 1.5V, V_{IN} = GND to 3.0V

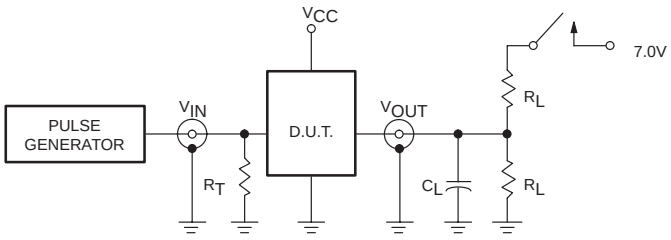


Waveform 1. Input to Output Propagation Delays

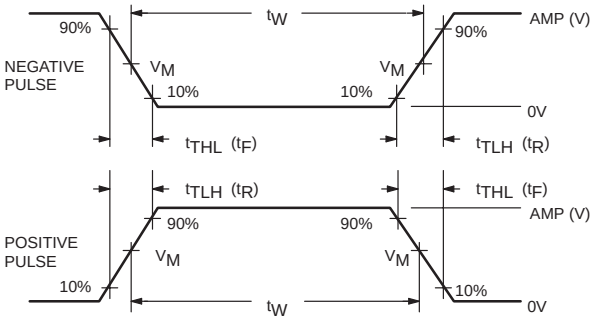


Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT



Test Circuit for 3-State Outputs



V_M = 1.5V
Input Pulse Definition

SWITCH POSITION

TEST	SWITCH
t_{PLZ}	closed
t_{PZL}	closed
All other	open

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

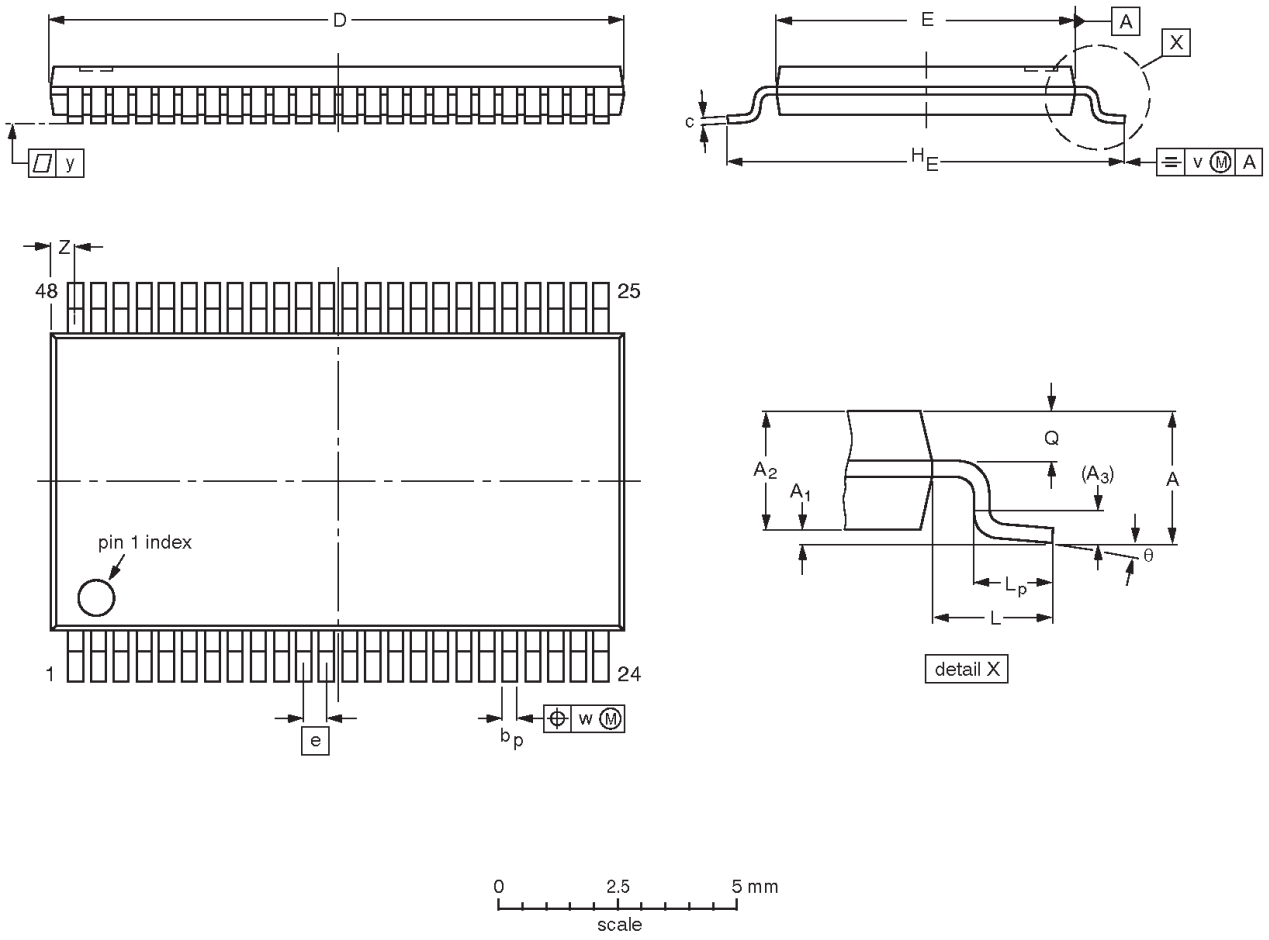
C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	t_W	t_R	t_F
74ABT/H16	3.0V	1MHz	500ns	2.5ns	2.5ns

SA00018

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm SOT362-1



DIMENSIONS (mm are the original dimensions).

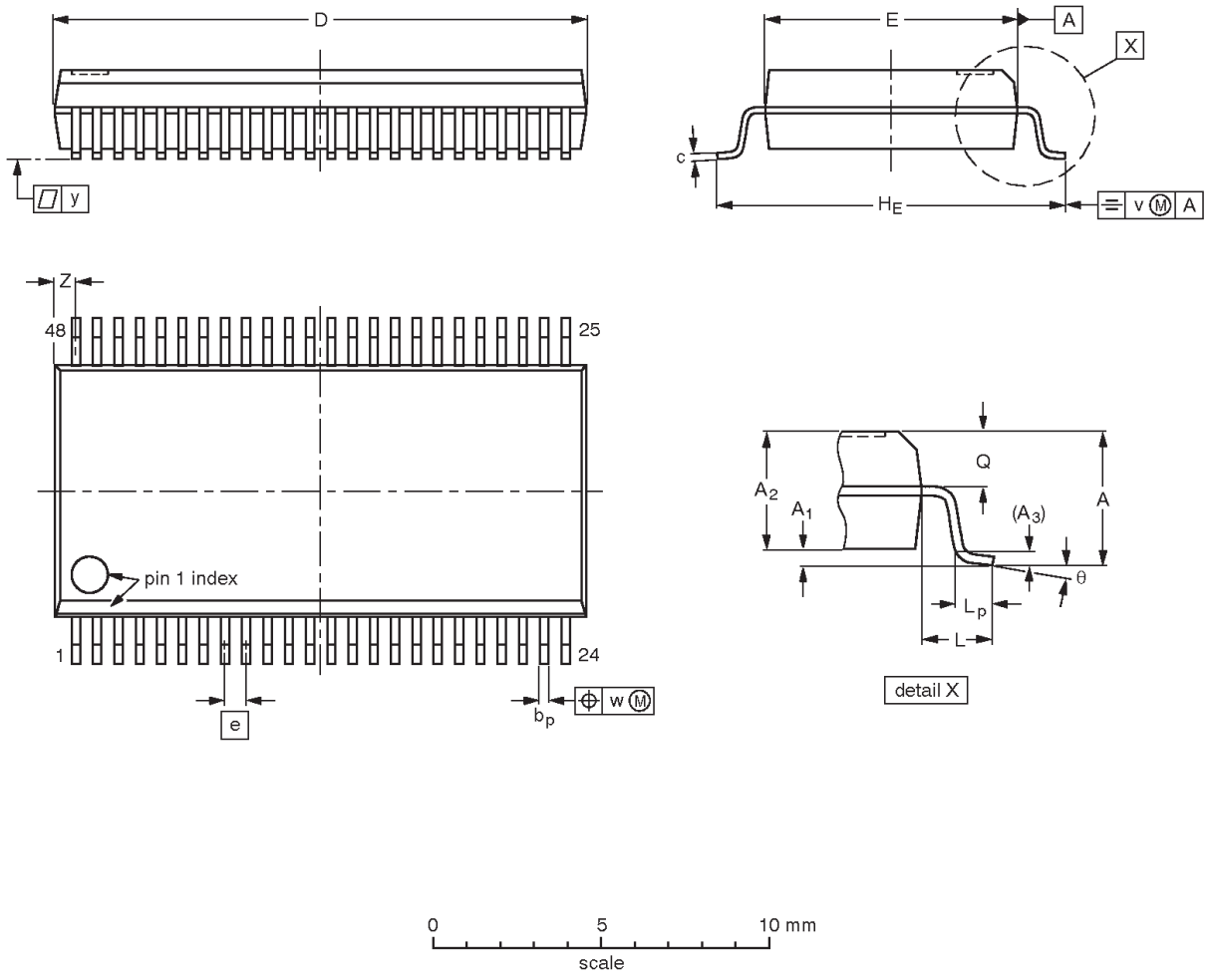
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ				
SOT362-1		MO-153					~~95-02-10~~ 99-12-27

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm **SOT370-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT370-1		MO-118				~~95-02-04~~ 99-12-27

REVISION HISTORY

Rev	Date	Description
_3	20021213	**Product data (9397 750 10854); ECN 853-1742 29296 of 12 December 2002. Supersedes data of 25 February 1998 (9397 750 03486).** Modifications: ● Ordering information table: remove “North America” column; remove 74ABTH16245BDGG package offering.
_2	19980225	**Product specification (9397 750 03486). ECN 853-1742 19018 of 25 February 1998. Supersedes data of 20 November 1996.**

Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Disclaimers

Life support — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes in the products—including circuits, standard cells, and/or software—described or contained herein in order to improve design and/or performance. When the product is in full production (status 'Production'), relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Contact information

For additional information please visit
http://www.semiconductors.philips.com. Fax: **+31 40 27 24825**

For sales offices addresses send e-mail to:
sales.addresses@www.semiconductors.philips.com.

Date of release: 12-02

Document order number: 9397 750 10854

Let's make things better.

Philips Semiconductors

PHILIPS